# **Power MOSFET**

# –60 V, 14 m $\Omega$ , –64 A, Single P–Channel

#### **Features**

- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- High Current Capability
- Avalanche Energy Specified
- NVMFS5113PLWF Wettable Flanks Product
- NVM Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage			$V_{DSS}$	-60	V
Gate-to-Source Voltage			$V_{GS}$	±20	V
Continuous Drain Cur-		$T_C = 25^{\circ}C$	I <sub>D</sub>	-64	Α
rent R <sub>θJC</sub> (Notes 1, 2, 3)	Steady	$T_C = 100^{\circ}C$		-45	
Power Dissipation R <sub>θJC</sub>	State	$T_C = 25^{\circ}C$	$P_{D}$	150	W
(Notes 1, 2)		T <sub>C</sub> = 100°C		75	
Continuous Drain Cur-	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	-10	Α
rent $R_{\theta JA}$ (Notes 1, 2, 3)		T <sub>A</sub> = 100°C		-7	
Power Dissipation R <sub>θJA</sub>		T <sub>A</sub> = 25°C	$P_{D}$	3.8	W
(Notes 1, 2)		T <sub>A</sub> = 100°C		1.9	
Pulsed Drain Current	$T_A = 25^{\circ}$	C, $t_p = 10 \mu s$	I <sub>DM</sub>	-415	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C
Source Current (Body Diode)			I <sub>S</sub>	-150	Α
Single Pulse Drain-to-Source Avalanche Energy (T <sub>J</sub> = 25°C, V <sub>DD</sub> = 50 V, V <sub>GS</sub> = 10 V, $I_{L(pk)}$ = 46 A, L = 0.3 mH, $R_G$ = 25 $\Omega$ )			E <sub>AS</sub>	315	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Drain) (Note 2)	$R_{\theta JC}$	1.0	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	°C/W

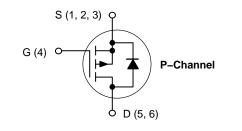
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- 3. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

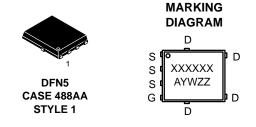


### ON Semiconductor®

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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
-60 V	14 mΩ @ –10 V	-64 A
	22 mΩ @ –4.5 V	-0 <del>4</del> A





A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information on page 5 of this data sheet.

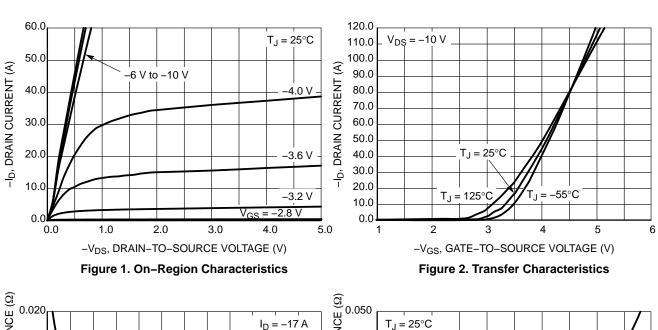
## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

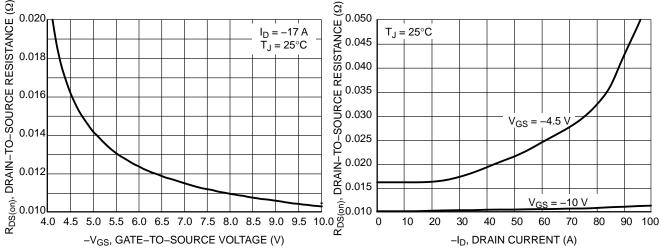
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•			•	•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$		-60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -60 \text{ V}$	T <sub>J</sub> = 25°C			-1.0	μΑ
			T <sub>J</sub> = 125°C			-100	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$				±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$		-1.5		-2.5	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = -10 \text{ V}, I_D = -17 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$			10.5	14	mΩ
					16	22	
Froward Transconductance	9FS	$V_{DS} = -15 \text{ V}, I_{D} = -15 \text{ A}$			43		S
CHARGES AND CAPACITANCES			•				
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V, } f = 1.0 \text{ MHz,}$ $V_{DS} = -25 \text{ V}$			4400		pF
Output Capacitance	C <sub>oss</sub>				505		1
Reverse Transfer Capacitance	C <sub>rss</sub>				319		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{DS} = -48 \text{ V},$ $I_{D} = -17 \text{ A}$	$V_{GS} = -4.5 \text{ V}$		45		nC
			$V_{GS} = -10 \text{ V}$		83		
Threshold Gate Charge	Q <sub>G(TH)</sub>	$V_{GS} = -10 \text{ V}, V_{DS} = -48 \text{ V},$ $I_D = -17 \text{ A}$			4		
Gate-to-Source Charge	$Q_{GS}$				13		
Gate-to-Drain Charge	$Q_{GD}$				27		
Plateau Voltage	$V_{GP}$				3.5		V
SWITCHING CHARACTERISTICS (No	otes 4)						
Turn-On Delay Time	t <sub>d(on)</sub>				15		ns
Rise Time	t <sub>r</sub>	$V_{GS} = -10 \text{ V, V}$	ns = -48 V.		37		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS} = -10 \text{ V}, V_{DS} = -48 \text{ V},$ $I_{D} = -17 \text{ A}, R_{G} = 2.5 \Omega$			54		
Fall Time	t <sub>f</sub>				77		
DRAIN-SOURCE DIODE CHARACTE	RISTICS					•	
Forward Diode Voltage	oltage $V_{SD}$ $V_{GS} = 0 \text{ V}, I_{S} = -17 \text{ A}$		T <sub>J</sub> = 25°C		-0.79	-1.0	V
		$I_S = -17 A$	T <sub>J</sub> = 125°C		-0.65		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{s}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{s} = -17 \text{ A}$			41		ns
Charge Time	ta				22		1
Discharge Time	t <sub>b</sub>				19		1
Reverse Recovery Charge	Q <sub>RR</sub>				50		nC

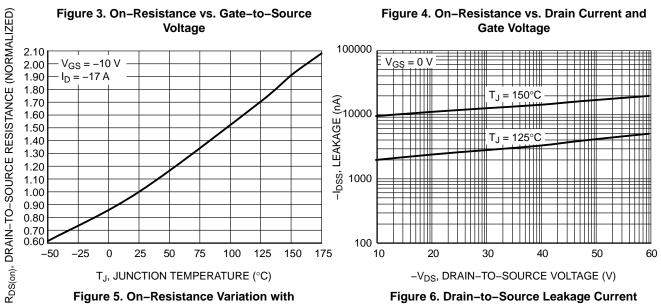
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%.

### **TYPICAL CHARACTERISTICS**







**Temperature** 

vs. Voltage

### **TYPICAL CHARACTERISTICS**

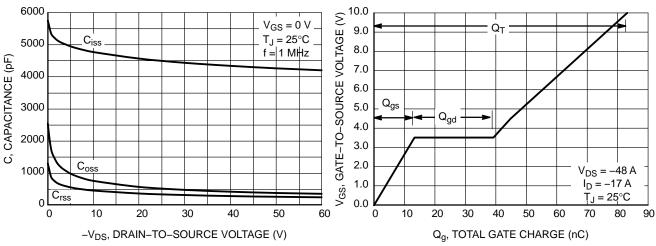


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Charge

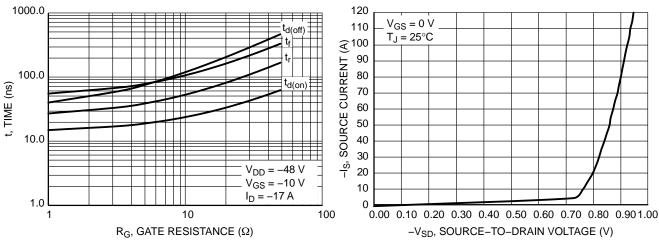


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

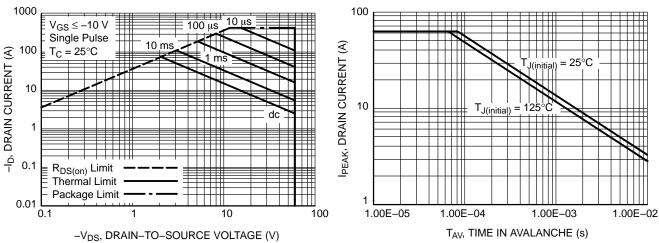


Figure 11. Maximum Rated Forward Biased Safe Operating Area

Figure 12. Avalanche Characteristics

### **TYPICAL CHARACTERISTICS**

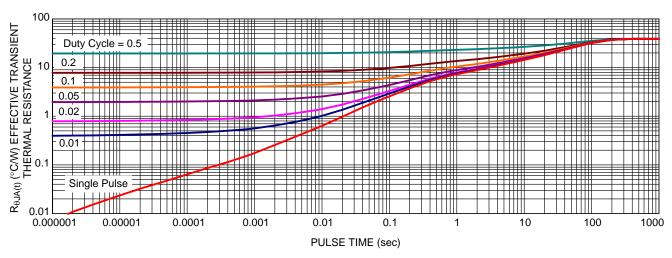


Figure 13. Thermal Response

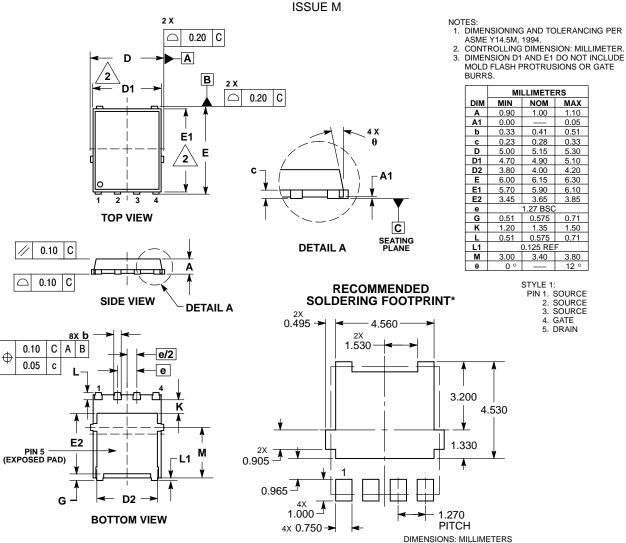
#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5113PLT1G	V5113L	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5113PLWFT1G	5113LW	DFN5 (Pb-Free)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

### DFN5 5x6, 1.27P (SO-8FL) CASE 488AA



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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